

04-29-2003

Form PTO-1595

(Rev. 10/02)

OMB No. 0651-0027 (exp. 6/30/2005)

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102433481

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jeffrey M. Peterson

4. 18. 03

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Nature of conveyance:



Assignment



Merger



Security Agreement



Change of Name



Other

15APR2003

Execution Date: _____

2. Name and address of receiving party(ies)

Name: Raytheon Company

Internal Address: _____

Office of the General Counsel

Street Address: 141 Spring Street

City: Lexington State: MA Zip: 02421

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 04/15/2003

A. Patent Application No.(s) _____

B. Patent No.(s) _____

10418870

Additional numbers attached? ☐ Yes ☒ No

4. Name and address of party to whom correspondence concerning document should be mailed:

Name: Raytheon Company

Internal Address: EO/E01/E150

Intellectual Property & Licensing

P. O. Box 902

Street Address: 2000 East El Segundo Boulevard

City: El Segundo State: CA Zip: 90245

5. Total number of applications and patents involved: 1

6. Total fee (37 CFR 3.41).....\$ 40.00



Enclosed



Authorized to be charged to deposit account

7. Deposit account number:

50-0616

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8. Signature.

William C. Schubert (Reg. 30,102)

Name of Person Signing

Signature

April 17, 2003

Date

Total number of pages including cover sheet, attachments, and documents: 4

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 2023104/28/2003 DBYRNE 00000067 500616 10418870
1 FC:1021 40.00 CHPATENT
REEL: 013993 FRAME: 0260

ASSIGNMENT

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Attorney Docket No. 02W122

WHEREAS, I, as below named sole inventor (if only one name is listed below) or joint inventor (if plural names are listed below) of the city and state as stated below next to my name, have invented a (an)

**Method For Preparing A Device Structure Having A Wafer Structure
Deposited On A Composite Substrate Having A Matched Coefficient Of
Thermal Expansion**

for which application for Letters Patent of the United States has been executed by me, or *(if the following is completed)*
was filed on _____ as Application No. _____ and

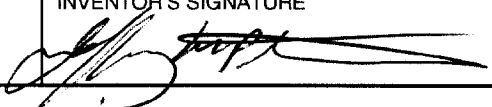
WHEREAS, RAYTHEON COMPANY (hereinafter referred to as RAYTHEON), a Delaware corporation, having its principal place of business in Lexington, Massachusetts, is desirous of acquiring the entire and exclusive right, title and interest in, to and under said invention, said application and any and all Letters Patent that may be granted therefor in the United States and throughout the world;

NOW, THEREFORE, in consideration of the obligations voluntarily assumed by me and set forth in an invention agreement between me and my employer, effective the date as stated below next to my name, and other good and valuable consideration, receipt of which is hereby acknowledged, I do hereby sell, assign and transfer to RAYTHEON, its successors, assigns or other legal representatives, the entire and exclusive right, title and interest in and to said invention invented by me, to said application and any and all applications which are continuations, continuations-in-part, divisions or substitutes of said application and any and all Letters Patent that may be granted therefor in the United States and throughout the world on any of said applications and to any and all reexaminations, reissues, renewals or extensions of said Letters Patent in the United States and throughout the world for the full term or terms for which said Letters patent may be granted in the United States and throughout the world; authorize and request the Director of the United States Patent and Trademark Office and all foreign countries to issue all such Letters Patent to said RAYTHEON, its successors, assigns or other legal representatives; covenant that no assignment, sale, agreement, transfer or encumbrance has been, or will be, made or entered into which would conflict with this assignment, sale and transfer; and agree to communicate to RAYTHEON, its successors, assigns or other legal representatives, upon request and at no cost or expense to me, any facts known by me respecting said invention, do all lawful acts, including the execution and delivery of all papers and proper oaths and giving of testimony that is deemed necessary or desirable by RAYTHEON, its successors, assigns or other legal representatives with regard to said invention for protecting, obtaining, maintaining and enforcing any and all of said Letters Patent in the United States and throughout the world for said invention and for perfecting, affirming, recording and maintaining the title of RAYTHEON, its successors, assigns or other legal representatives, and generally cooperate to the fullest extent in all matters pertaining to said invention, and any and all of said Letters Patent and the title thereto in RAYTHEON, its successors, assigns or other legal representatives.

Title : Method For Preparing A Device Structure Having A Wafer Structure Deposited On A Composite Substrate Having A Matched Coefficient Of Thermal Expansion

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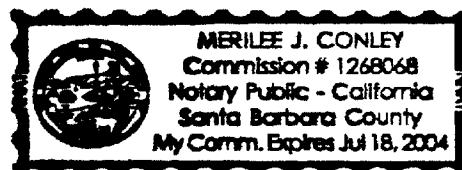
IN WITNESS WHEREOF, I have executed this instrument.

FULL NAME OF SOLE OR JOINT INVENTOR Jeffrey M. Peterson	INVENTOR'S SIGNATURE 	DATE SIGNED 4/15/03
RESIDENCE (CITY AND STATE) Santa Barbara, California		INVENTION AGREEMENT DATE 8 September 1986

STATE OF CALIFORNIA)

COUNTY OF SANTA BARBARA)

SS:

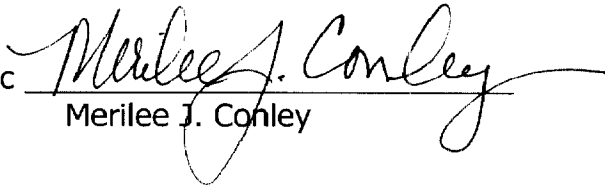


On April 15, 2003, before me, Merilee J. Conley, a Notary Public in and for said State, personally appeared **JEFFREY M. PETERSON**

☐ personally known to me or ☒ proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

WITNESS my hand and official seal.

Notary Public


Merilee J. Conley